05/14/2018 504913408

PATENT ASSIGNMENT COVER SHEET

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SUBMISSION TYPE:	NEW ASSIGNMENT
NATURE OF CONVEYANCE:	ASSIGNMENT

CONVEYING PARTY DATA

Name	Execution Date
GLEB VYACHESLAVOVICH KALACHEV	05/07/2018
IVAN LEONIDOVICH MAZURENKO	04/28/2018
ELYAR ELDAROVICH GASANOV	04/28/2018
CARMELA COZZO	04/30/2018
JIE JIN	05/07/2018

RECEIVING PARTY DATA

Name:	FUTUREWEI TECHNOLOGIES, INC.
Street Address:	5340 LEGACY DRIVE
Internal Address:	SUITE 175
City:	PLANO
State/Country:	TEXAS
Postal Code:	75024

PROPERTY NUMBERS Total: 1

Property Type	Number
Application Number:	15978678

CORRESPONDENCE DATA

Fax Number: (972)732-9218

Correspondence will be sent to the e-mail address first; if that is unsuccessful, it will be sent using a fax number, if provided; if that is unsuccessful, it will be sent via US Mail.

Phone: (972) 732-1001

docketing@slatermatsil.com Email:

Correspondent Name: SLATER MATSIL, LLP Address Line 1: 17950 PRESTON ROAD

Address Line 2: **SUITE 1000**

Address Line 4: DALLAS, TEXAS 75252

ATTORNEY DOCKET NUMBER:	HW 85437158US02
NAME OF SUBMITTER:	GINA MARTINEZ
SIGNATURE:	/Gina Martinez/
DATE SIGNED:	05/14/2018

PATENT REEL: 045797 FRAME: 0191

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Total Attachments: 3

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PATENT REEL: 045797 FRAME: 0192

ASSIGNMENT

WHEREAS, I/We, the undersigned inventor(s) (or one of the undersigned joint inventors), of residence as listed below, having invented certain new and useful improvements as below entitled, for which application for United States Letters Patent is made, the said application having been executed on the date set forth below; and

WHEREAS, Futurewei Technologies, Inc. ("Assignee"), a corporation organized and existing under the laws of Texas, with its principal office at 5340 Legacy Drive, Suite 175, Plano, TX 75024 is desirous of acquiring my/our entire right, title and interest in the said invention, and to the said application and any Letters Patent that may issue thereon in the United States and all other countries throughout the world;

NOW, THEREFORE, for good and valuable consideration, the receipt and sufficiency of which are hereby acknowledged, I/we will assign, and hereby assign and transfer to the Assignee and the Assignee's legal representatives, successors and assigns the full and exclusive right, title and interest in and to the invention in the United States and every foreign country and the entire right, title, and interest in and to the patent application and other such applications (e.g., provisional applications, non-provisional applications, continuations, continuations-in-part, divisional, reissues, reexaminations, National Phase applications, including petty patent applications, and utility model applications) that may be filed in the United States and every foreign country on the invention, and the patents, extensions, or derivations thereof, both foreign and domestic, that may issue thereon, and I/we do hereby authorize and request the Commissioner for Patents to issue U.S. patents for said invention, or patent resulting therefrom, insofar as my interest is concerned, to the Assignee agreeably with the terms of this assignment document.

I also hereby agree to sell and to assign, and sell and assign to Assignee, its successors and assigns, my foreign rights to the invention disclosed in said application, in all countries of the world, including, but not limited to, the right to file applications and obtain patents under the terms of the International Convention, and further agree to execute any and all patent applications, assignments, affidavits, and any other papers in connection therewith necessary to perfect such patent rights.

I hereby further agree that I will communicate to Assignee, or its successors, assigns, and legal representative, any facts know to me respecting said invention or the file history thereof, and at the expense of said assignee company, testify in any legal proceedings, sign all lawful papers, execute all divisional, continuation, reissue and substitute applications, make all lawful oaths, and generally do everything possible to aid such Futurewei, its successors, assigns and nominees to obtain and enforce proper patent protection for said invention in all countries.

Futurewei Technologies, Inc. Patent Reference No. HW 85437158US02

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PATENT REEL: 045797 FRAME: 0193

ASSIGNMENT

IN WITNESS WHEREOF, I hereunto set my hand and seal this day and year;

Title of Invention	Compact Low Density Parity Check (LDPC) Base Grap	
	Appl. No.	Filing Date:
Signature of Inventor	Kasarel	
Inventor Name	Gleb Vyacheslavovich Kalachev	
Date	05707/2018	
Residence (City/State)	Moscow, Russia	
Signature of Inventor	<i>9</i> 5	
Inventor Name	Ivan Éronidovich Mazurenko	
Date	04/28/2018	
Residence (City/State)	Khimki, Russia	
Signature of Inventor	///ja	
Inventor Name	Elyar Eldarovich Gasanov	
Date	04/23/20/3	
Residence (City/State)	Moscow, Russia	
Signature of Inventor		
Inventor Name	Carmela Cozzo	
Date		
Residence (City/State)	San Diego, CA, USA	
Signature of Inventor	26 Per	
Inventor Name	Jie Jin	
Date	07/05/2019	
Residence (City/State)	Moscow, Russia	

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ASSIGNMENT

IN WITNESS WHEREOF, I hereunto set my hand and seal this day and year;

Title of Invention	Compact Low Density Parity Check (LDPC) Base Graph	
	Appl. No.	Filing Date:
Signature of		
Inventor		
Inventor Name	Gleb Vyacheslavovich Kalachev	
Date		
Residence	Moscow, Russia	
(City/State)		
Signature of		
Inventor		
Inventor Name	Ivan Leonidovich Mazurenko	
Date		
Residence	Khimki, Russia	
(City/State)		
Signature of		
Inventor		
Inventor Name	Elyar Eldarovich Gasanov	
Date		
Residence	Moscow, Kussia	
(City/State)		
Signature of	A . 1) .	
Inventor	Conulelo400	
Inventor Name	Carmela Cezzo	
Date	4/30/2018	
Residence	San Diego, CA, USA	
(City/State)		
Signature of		
Inventor		
Inventor Name	Jie Jin	
Date		
Residence	Moscow, Russia	
(City/State)		

Futurewei Technologies, Inc. Patent Reference No. HW 85437158US02

RECORDED: 05/14/2018

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